

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUS200N08S5N023	**Issued**	15. May 2021
MA#	MA005344492		
Package	PG-HSOG-8-1	**Weight***	703.75 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.865	0.55	0.55	5492	5492
leadframe	inorganic material	phosphorus	7723-14-0	0.040	0.01		57	
	non noble metal	iron	7439-89-6	0.134	0.02		191	
	non noble metal	copper	7440-50-8	134.219	19.07	19.10	190720	190968
wire	non noble metal	aluminium	7429-90-5	12.474	1.77	1.77	17724	17724
encapsulation	inorganic material	zincoxide	1314-13-2	2.650	0.38		3766	
	miscellaneous	miscellaneous	-	10.601	1.51		15064	
	plastics	epoxy resin	-	39.753	5.65		56488	
	inorganic material	silicondioxide	60676-86-0	212.019	30.13	37.67	301270	376588
leadfinish	non noble metal	tin	7440-31-5	8.309	1.18	1.18	11807	11807
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.220	0.03	0.03	312	313
solder	non noble metal	tin	7440-31-5	0.068	0.01		97	
	noble metal	silver	7440-22-4	0.085	0.01		121	
	non noble metal	lead	7439-92-1	3.247	0.46	0.48	4614	4832
heatspreader	inorganic material	phosphorus	7723-14-0	0.083	0.01		118	
	non noble metal	iron	7439-89-6	0.276	0.04		392	
	non noble metal	copper	7440-50-8	275.705	39.17	39.22	391766	392276
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com